

INTERNATIONAL STANDARD

NORME INTERNATIONALE



**Device embedding assembly technology –
Part 2-5: Guidelines – Implementation of a 3D data format for device embedded
substrate**

**Technologie d'ensemble avec appareil(s) intégré(s) –
Partie 2-5: Lignes directrices – Mise en œuvre d'un format de données 3D
pour un substrat avec appareil(s) intégré(s)**



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IEC Central Office
3, rue de Varembe
CH-1211 Geneva 20
Switzerland

Tel.: +41 22 919 02 11
info@iec.ch
www.iec.ch

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CONTENTS

FOREWORD.....	5
1 Scope.....	7
2 Normative references	7
3 Terms and definitions	7
4 Data definition	10
4.1 Flow chart design of device embedded substrate	10
4.2 Applicable range.....	11
4.2.1 Product.....	11
4.2.2 Process	12
4.3 Features	13
4.3.1 General	13
4.3.2 Device embedded substrate structure	13
4.3.3 SiP interposer structure	14
4.3.4 Virtual layer description	15
4.3.5 Terminal structure and embedded device structure including an SiP.....	15
4.3.6 Total design data of an SiP and device embedded substrate	15
4.4 Data description summary.....	16
4.4.1 Type of data and structures	16
4.4.2 File structure	18
4.5 3D expression.....	19
4.5.1 General	19
4.5.2 Coordinates.....	19
4.5.3 Position description	20
4.5.4 Relation between coordinate origin and board position	20
4.6 Layer concept	21
4.7 Substrate data	21
4.7.1 General	21
4.7.2 Layer map information	22
4.7.3 Device arrangement information	23
4.7.4 Basic figures.....	25
4.7.5 Net information	31
4.7.6 Artwork information.....	32
4.7.7 Package information	32
4.7.8 External port information.....	33
4.7.9 Internal port information.....	33
4.7.10 User expansion information	33
4.8 Defined data	33
4.8.1 General	33
4.8.2 Layer definition.....	33
4.8.3 Land definition.....	34
4.8.4 Via definition	35
4.8.5 Device definition	36
4.8.6 User expansion definition	37
5 Data organization and data description based on XML schema.....	38
5.1 General.....	38
5.2 Data organization of Example 1	38
5.3 Data description of layer stack-up	39

5.4	Data description of device	43
5.5	Data organization of layer	47
5.6	Data description of via	50
5.7	Data description of land	51
	Bibliography	53
Figure 1	– Flow chart of design of device embedded substrate	11
Figure 2	– General structure of device embedded substrate	12
Figure 3	– Example of device embedded substrate structure	14
Figure 4	– Examples of SiPs	14
Figure 5	– Example of virtual layer description	15
Figure 6	– Terminal structure	15
Figure 7	– Structure of SiP on a device embedded substrate	16
Figure 8	– Data structure	18
Figure 9	– One file structure (recommended)	19
Figure 10	– Two file structure	19
Figure 11	– Definition of coordinates	20
Figure 12	– Position definition	20
Figure 13	– Relation between coordinates and board position	21
Figure 14	– Layer concept	21
Figure 15	– Layer construction	22
Figure 16	– Simplified layer construction	23
Figure 17	– Layer definition of pad connection	24
Figure 18	– Layer definition of via connection	24
Figure 19	– Rotation direction on <i>X</i> , <i>Y</i> , and <i>Z</i> axes	25
Figure 20	– Point	26
Figure 21	– Area	27
Figure 22	– Lines	27
Figure 23	– Letters	28
Figure 24	– Letter shape	28
Figure 25	– Bonding wire information	29
Figure 26	– Semi-sphere	29
Figure 27	– Truncated pyramid	30
Figure 28	– Via	30
Figure 29	– Device definition	31
Figure 30	– Group	31
Figure 31	– Data structure of net information	32
Figure 32	– Relation of layer definition data	34
Figure 33	– Land definition	35
Figure 34	– Relation between hole information and land information	36
Figure 35	– Device with internal connection information	37
Figure 36	– Device without internal connection information	37
Figure 37	– Cross sectional view of Example 1	38
Figure 38	– Data organization of Example 1	38

Figure 39 – Data description of Example 1 39

Figure 40 – Layer structure of Example 1 40

Figure 41 – Data description of layer stack-up 42

Figure 42 – Configuration of device 1 43

Figure 43 – Data description of device 1 44

Figure 44 – Configuration of device 2 45

Figure 45 – Data description of device 2 46

Figure 46 – Layer view of Example 1 48

Figure 47 – Data description of layers 50

Figure 48 – Type of vias 51

Figure 49 – Data description of vias 51

Figure 50 – Type of lands 52

Figure 51 – Data description of lands 52

Table 1 – Required information 13

Table 2 – List of data 17

INTERNATIONAL ELECTROTECHNICAL COMMISSION

DEVICE EMBEDDING ASSEMBLY TECHNOLOGY –**Part 2-5: Guidelines – Implementation of a 3D data format
for device embedded substrate**

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International Standard IEC 62878-2-5 has been prepared by IEC technical committee 91: Electronics assembly technology.

This bilingual version (2020-01) corresponds to the monolingual English version, published in 2019-09.

This first edition cancels and replaces IEC PAS 62878-2-5 published in 2015. This edition constitutes a technical revision.

This edition includes the following significant technical changes with respect to the previous edition:

- a) the title has been changed to "Implementation of a 3D data format for device embedded substrate" from "Requirements of design data format for device embedded substrate";
- b) the scope of this implementation has changed to not include SiPs.

The text of this International Standard is based on the following documents:

CDV	Report on voting
91/1557/CDV	91/1589/RVC

Full information on the voting for the approval of this International Standard can be found in the report on voting indicated in the above table.

The French version of this standard has not been voted upon.

This document has been drafted in accordance with the ISO/IEC Directives, Part 2.

A list of all parts in the IEC 62878 series, published under the general title *Device embedding assembly technology*, can be found on the IEC website.

Future standards in this series will carry the new general title as cited above. Titles of existing standards in this series will be updated at the time of the next edition.

The committee has decided that the contents of this document will remain unchanged until the stability date indicated on the IEC website under "<http://webstore.iec.ch>" in the data related to the specific document. At this date, the document will be

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- amended.

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DEVICE EMBEDDING ASSEMBLY TECHNOLOGY –

Part 2-5: Guidelines – Implementation of a 3D data format for device embedded substrate

1 Scope

This part of IEC 62878 specifies requirements based on XML schema that represents a design data format for device embedded substrate, which is a board comprising embedded active and passive devices whose electrical connections are made by means of a via, electroplating, conductive paste or printing of conductive material.

This data format is to be used for simulation (e.g. stress, thermal, EMC), tooling, manufacturing, assembly, and inspection requirements. Furthermore, the data format is used for transferring information among printed board designers, printed board simulation engineer, manufacturers, and assemblers.

This part of IEC 62878 applies to substrates using organic material. It neither applies to the re-distribution layer (RDL) nor to the electronic modules defined as M-type business model in IEC 62421.

2 Normative references

There are no normative references in this document.

3 Terms and definitions

For the purposes of this document, the following terms and definitions apply.

ISO and IEC maintain terminological databases for use in standardization at the following addresses:

- IEC Electropedia: available at <http://www.electropedia.org/>
- ISO Online browsing platform: available at <http://www.iso.org/obp>

3.1

artwork information

information that shows a SiP not included in net and figure data in board (symbol mark, inside of SiP, mould, spacer, remarks, etc.)

3.2

board information

total information of a device-embedded substrate, including embedded devices

3.3

chip stack

package of semiconductor chips stacked vertically

3.4

clearance

area around a through-hole where there is no conductor to prevent electrical connection between a large conductor area, such as that of a power supply or a ground and a plated through-hole